



1 *Wire web and manufactured wafer.*

## WIRE AND PROCESS BENCHMARKING

### Expertise

Our advanced process data and wafer geometry analysis allows

- The detection of the performance limit of sawing wires
- A process development for all current wafering technologies: diamond wire, structured wire, straight wire

### Our Services

#### For Wafer Manufacturers –

Decrease your wafering costs by optimizing your processes

- ➔ Performing wafering runs und detect the wafer geometry
- ➔ Process evaluation for all wire and wafering technologies
- ➔ Identifying time consuming process steps to save consumables

#### For Wire Suppliers –

Raise your sales volume with high performance wire

- ➔ Performing independent wire benchmark test
- ➔ Identifying individual wire performance
- ➔ Quantifying the correlation between wire performance and wafer quality

#### Fraunhofer Center for Silicon Photovoltaics CSP

Otto-Eissfeldt-Strasse 12  
06120 Halle (Saale) | Germany

#### Contact

Ringo Koepge  
Telephone +49 345 5589 5311  
ringo.koepge@csp.fraunhofer.de

[www.csp.fraunhofer.de](http://www.csp.fraunhofer.de)

1 Optical wafer inspection.

Quantification Approach for Wire Performance<sup>1</sup>

- Wafer geometry data are taken from conventional inspection tools and correlated to a calculated wire usage.
- The wire usage is defined as the amount of new silicon surface that was created by the wire and normalized to the wire length, the so called specific silicon removal area (cm<sup>2</sup>/m).

The detection of a characteristic correlation between the wire usage and the wafer geometry provides the following performance parameters:

I - LTV<sub>0</sub> - Initial Level of LTV [μm]

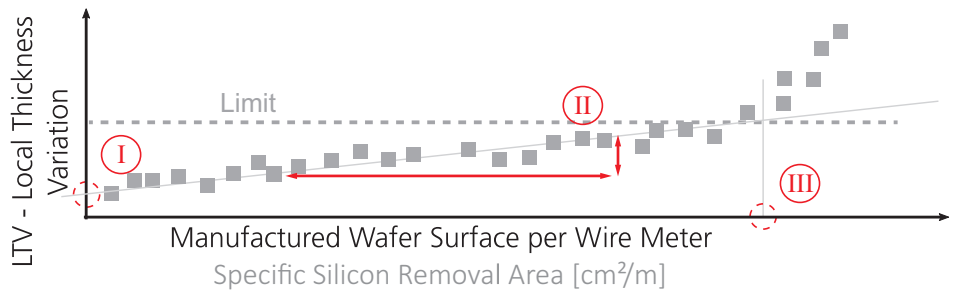
Depends on wire type

II - m<sub>LTV</sub> - LTV Gradient [μm / (cm<sup>2</sup>/m)]

Affected by wire type and process

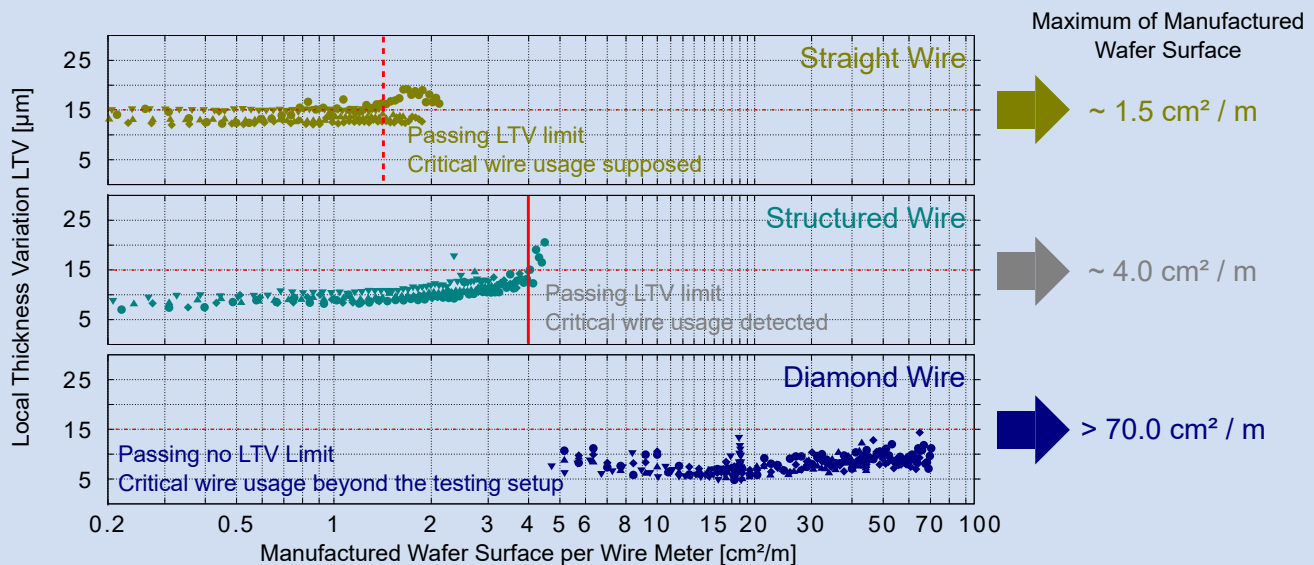
III - Critical Wire Usage [cm<sup>2</sup>/m]

Limit of wire performance



<sup>1</sup>Koepge, R., Brinnig, S., Kaule, F., Schwabe, H., Schoenfelder, S., »Advanced Analysis of Multi Wire Wafering Processes«, 44<sup>th</sup> IEEE Photovoltaic Specialists Conference (PVSC-44), Washington D.C. (U.S.A.), 2017

Experimental Data<sup>2</sup>



2 Detection of the wire performance with respect to the wafer geometry for three different wafering technologies.<sup>2</sup>

<sup>2</sup>Koepge, R., Brinnig, S., Kaule, F., Schwabe, H., Schoenfelder, S., »Advanced Analysis of Multi Wire Sawing Processes and Wire Performance Detection«, 33<sup>th</sup> EUPVSEC, Amsterdam (Netherlands), 2017